

What is claimed is:

1. A circuit board, the circuit board characterized by comprising:
 - a substrate;
 - a first component which is mounted on said substrate by solder connection;
 - a second component which is mounted on said substrate with an anisotropic conductive film interposed therebetween; and
 - a band-shaped region which extends in the shape of a band while including said second component, and which does not include said first component.
2. A circuit board according to claim 1, characterized in that said first component is a passive element or a mechanism component, while said second component is a semiconductor device.
3. A circuit board according to claim 1, characterized in that said band-shaped region is wider than a pressing surface of a thermocompression bonding head which is employed in mounting said second component.
4. A circuit board according to claim 1, characterized in that an alignment mark is provided outside said belt-shaped region.
5. A circuit board according to claim 1, characterized in that the solder connection includes a reflow treatment.
6. A circuit board according to claim 1, characterized in that a plurality of said first components are disposed, and that said band-shaped region is located between the plurality of first components.
7. A circuit board according to claim 6, characterized in that said second component is a power source IC or a power source LSI.
8. A circuit board according to claim 1, characterized in that said band-shaped region is disposed extending from one end to another end of said substrate.

9. A circuit board according to claim 1, characterized in that said band-shaped region extends rectilinearly.

10. A circuit board according to claim 1, characterized in that wiring patterns are formed in said band-shaped region.

11. A circuit board according to claim 1, characterized in that a dummy electrode is formed at a position on said substrate corresponding to said second component.

12. A display device characterized by comprising said circuit board of the construction defined in claim 1, and display means to which said circuit board is connected.

13. A display device according to claim 12, characterized in that said display means is constructed of a liquid crystal device which includes substrates, and that said circuit board is connected to said substrates.

14. A display device according to claim 12, characterized in that a plurality of said first components are disposed, that said band-shaped region is located between the plurality of first components, and that said second component is a power source IC, a power source LSI, a liquid crystal driving IC or a liquid crystal driving LSI.

15. A method of manufacturing a circuit board characterized by comprising:
the step of mounting a first component on a substrate by solder connection;
the step of arranging an anisotropic conductive film on a predetermined position of the substrate;
the step of arranging a second component on the anisotropic conductive film; and
the step of thermocompression-bonding the second component to said substrate with said anisotropic conductive film held therebetween;
wherein said step of arranging said anisotropic conductive film on the predetermined position of said substrate is performed after said step of mounting the first component on said substrate by the solder connection.

16. A method of manufacturing a circuit board according to claim 15, characterized in that said step of mounting said first component on said substrate by the solder connection includes a reflow treatment.